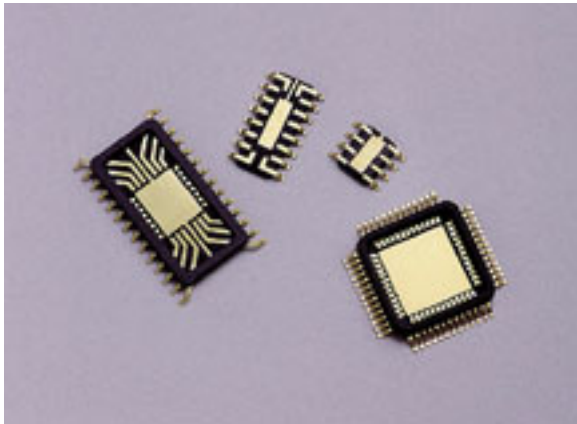


Plastic Equivalent Packages



StratEdge PTI Division announces the availability of a complete line of plastic equivalent packages (PEP), a glass walled surface mount package used for Bluetooth[®] semiconductors, C band VSAT amplifiers, cellular base station amplifiers, and semiconductors for wireless networking applications. At frequencies above 2 GHz the PEP packages provide improved electrical performance compared with traditional plastic packages and they can be hermetically sealed. These cavity based designs also provide improved long term reliability and can dissipate the heat generated by many of these high power and high frequency devices.

PEP packages are a good tool for testing of prototype die or for low volume production runs in developing markets. Because the PEP packages precisely match the outlines of the standard plastic packages, they are readily assembled and tested using standard tooling, equipment, and processes.

The PEP package construction uses a glass-ceramic composite material for the body combined with a gold plated Kovar lead frame for the conductors and metal die attach pad. Non-conductive die attach areas can also be provided.

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<http://www.wirelessdesignmag.com/product-releases/2001/11/plastic-equivalent-packages>